



ERS at Semicon Japan: Hall 7, booth 7D-724

## **ERS AirCool3 Thermal Wafer Chuck System maintains leadership in energy efficiency and cost-of-ownership**

**MUNICH – November 27, 2012** - ERS electronic GmbH, market leader in the field of Thermal Wafer Chucks in semiconductor production, will exhibit its successful AirCool 3 (AC3) wafer thermal test system at the Semicon Japan which will take place from December 5 to December 7 in Tokyo.

Wafer test is a strategic element in semiconductor production. The functional testing of the wafer early in the production process enables chip manufacturers to identify and single out faulty devices before they are packaged. This significantly reduces production costs.

During the thorough thermal tests performed on the semiconductor devices, the wafers are subjected to extreme temperatures of up to +300°C and down to -65°C. The ERS system utilizes air as coolant for the wafer for these temperature ranges instead of expensive liquid coolants. The high reliability and low running costs of ERS air cooled systems are unmatched in the market today. Due to its protected technology, the AC3 is extremely energy-efficient; no competing product can offer equal performance with such low consumption of dry air and electrical power. For these reasons the AC3 is the market leader for cold retrofits at chip makers world-wide.

Since the air coolant used in the ERS system operates throughout the entire temperature range, active heat dissipation applications are possible in the transition ranges of liquid coolants (typically between +50°C and +90°C). The AC3's modular concept and sophisticated electronics give it another important edge on the competition. In-the-field reprogramming of the thermal controller enables users to adjust the system to different test applications from low noise to high power dissipation. At Semicon Japan, the latest developments in the control electronics and algorithms will be presented by exhibiting a 300mm system specialized for parametric wafer test. Please visit us in Hall 7, booth 7D 724

For more information visit [www.ers-gmbh.com](http://www.ers-gmbh.com)

### **About ERS electronic GmbH:**

ERS electronic GmbH, located near Munich, is in its 40th year of supplying the most innovative thermal test solutions to the semiconductor industry. The most famous products are its fast-ramping and precise low-noise thermal chuck systems (-65°C to +500°C) for analytical, parametric and wafer sort probing up to 300mm. ERS also designs and builds stand-alone thermal-forcing systems and custom production tools for special applications. ERS invented the AirCool®, AirCool® plus and PowerSense® thermal chuck systems that have been fully integrated into all major manual, semi- and fully automatic wafer probers.

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